

V1.0.0

PIN Diode MMIC SP2T Reflective Switch 0.05-50GHz

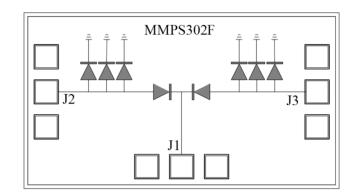
Features

- PIN Diode SP2T Reflective design
- Frequency:0.05-50GHz
- Isolation: 45dB Typical
- Insertion Loss: 0.9 dB Typical
- Control Voltage:+5/-5V
- Switching Speed: 10ns Typical
- Die Size: 1.3 x 0.725 x 0.1 mm

Typical Applications

- Voltage control
- Fast Switching Speed
- Low Insertion Loss and High Isolation
- Customization available upon request

Functional Block Diagram



Electrical Specifications

TA = +25°C, VCTL=+5/-5V , \pm 10 mA Typical

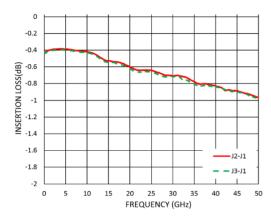
Parameters	Min.	Тур.	Max.	Units
Frequency	0.05		50	GHz
Insertion Loss		0.9	1.2	dB
Isolation	35	45		dB
Input Return Loss (ON State)		16		dB
Output Return Loss (OFF State)		16		dB
P1dB - Output 1dB Compression		27		dBm
IIP3-Input Third Order Intercept		40		dBm
Switching Speed		10		ns



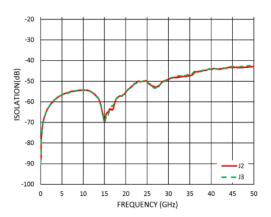
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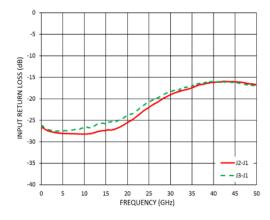
Insertion Loss vs. Frequency



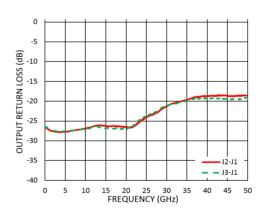
Isolation vs. Frequency



Input Return Loss vs. Frequency



Output Return Loss vs. Frequency





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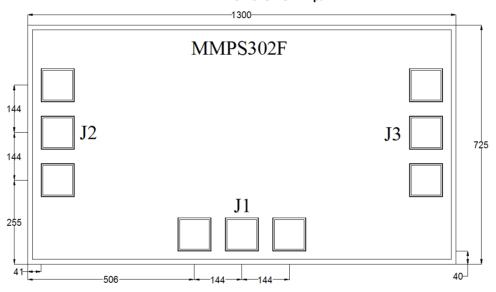
Absolute Maximum Ratings

Max Incident C.W. RF Power	+31dBm
DC Reverse Voltage	25V
Bias Current	±50 mA
Operating Temperature	-55°C to +85 °C
Storage Temperature	-55°C to +150 °C



Outline Drawing:

All Dimensions in µm



True Table

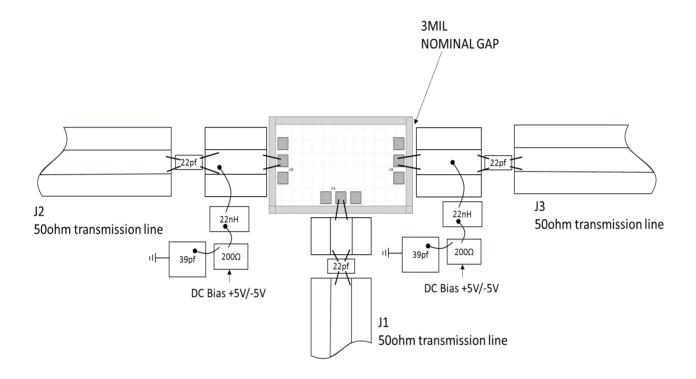
Control Voltage		State		
J2	J3	J2→J1	J3→J1	
-5V	+5V	ON	OFF	
+5V	-5V	OFF	ON	



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Assembly Drawing



Notes:

1. Die thickness: 100µm

Typical bond pad is 100*100µm²
Bond pad mentalization: Gold
Backside metallization: Gold

5. Backside of the die (GND)

6. No connection required for unlabeled bond pads

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